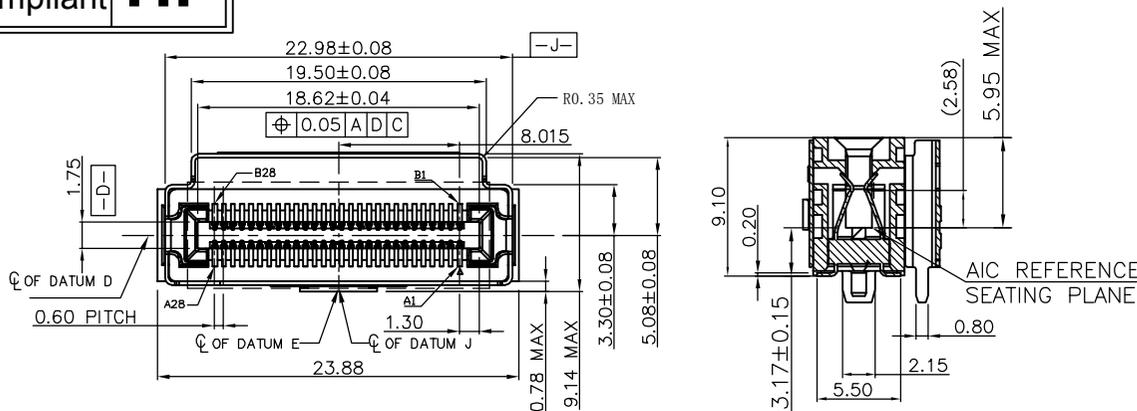


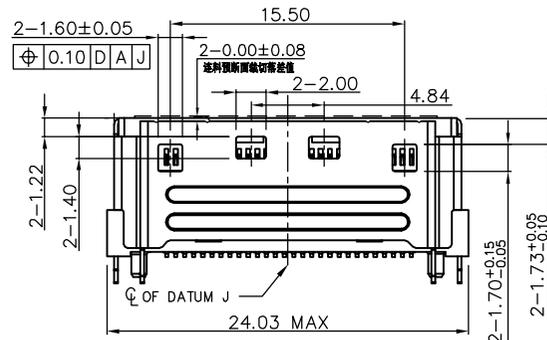
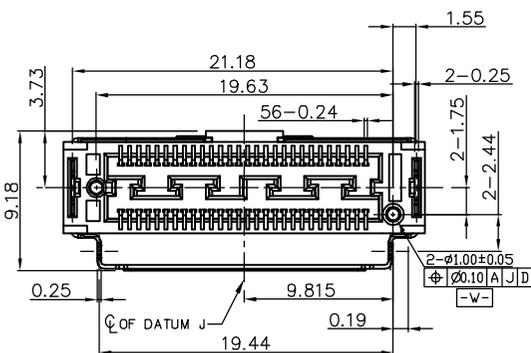
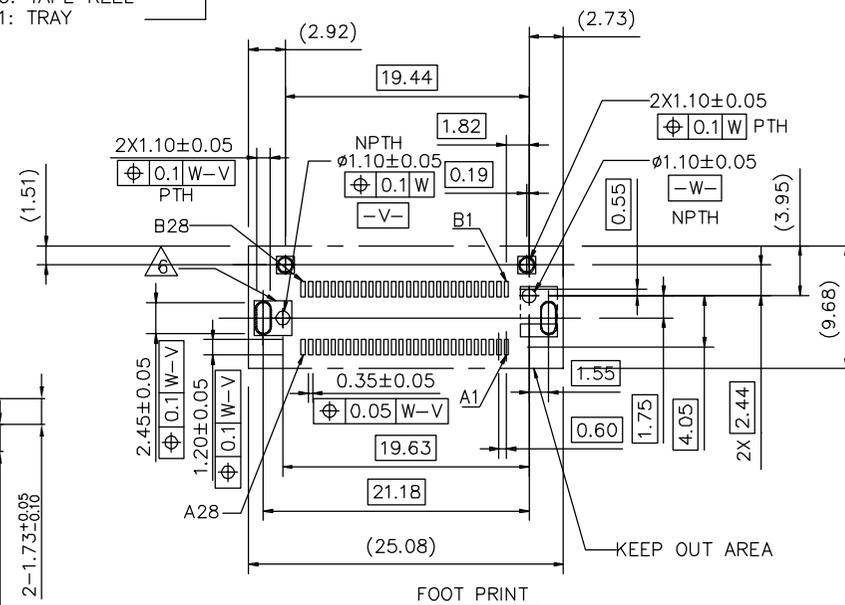
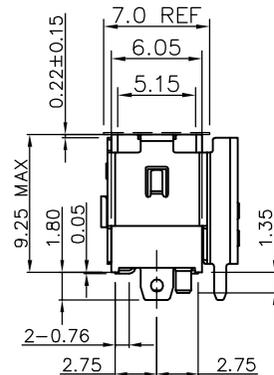
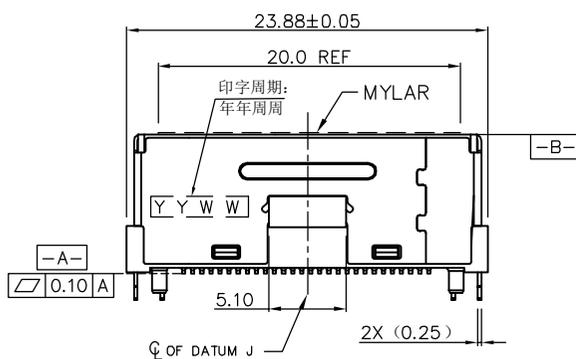
| REV. | ECN.NO. | MODIFY.CONTENT |
|------|------------|----------------|
| X1 | 2023-10-12 | NEW |



- NOTES:
- MATERIAL:
HOUSING: HIGH TEMPERATURE THERMOPLASTIC 94V-0, BLACK COLOR
TERMINAL: COPPER ALLOY
BOARD LOCK: COPPER ALLOY
SHELL: STAINLESS
 - PLATING:
TERMINAL: SELECTIVE Au (SEE ORDER INFORMATION) ON CONTACT AREA, MATTE TIN ON SOLDER TAIL AREA, BOTH OVER Ni UNDERPLATED.
 - THIS LAYOUT REFER TO THE SPECIFICATION OPC-NIC 3.0
 - MECHANICAL CHARACTERISTICS
 - MATING FORCE (MODULE TO CONNECTOR)
56PIN 1C = 30.8 N MAX.
 - MATING UNMATING FORCE
56PIN 1C = 2.8 N MIN.
 - DURABILITY: 200 CYCLES.
 - ELECTRICAL CHARACTERISTICS
 - CONTACT CURRENT RATING: 1.1AMPS . PER PIN.
 - INSULATION RESISTANCE: 1000 MEGOHMS
 - DIELECTRIC WITHSTANDING VOLTAGE:300 VAC CURRENT LEAKAGE:0.5mA MAX
 - LOW LEVEL CONTACT RESISTANCE:
INITIAL:30 MILLIOHMS MAX, DELTA:15 MILLIOHMS MAX.
 - OPERATING TEMPERATURE RANGE: -40°C TO +85°C .
 - THE PRODUCT DRAWING PER SFF-TA-1002 Rev:1.2

P/N: GENZ-*** L * * 3 **

056:56Pin 46: Au15u"/Sn80u"/Ni50u"
 0: WITH LOGO 47: Au30u"/Sn80u"/Ni50u"
 1: WITHOUT LOGO 3: TYPE C
 0: TAPE REEL
 1: TRAY



| GENERAL | TOLERANCE | DWG.NO. | GENZ-056L10300 | PART.NO. | GENZ-056L103** | DRAWN | TONY 2023-10-12 |
|----------|-----------|---------|----------------|----------|------------------------|----------|-----------------|
| x.±0.50 | x.±5° | REV. | X1 | TITLE | GEN Z 1C (SFF TA-1002) | CHECKED | |
| .x±0.25 | .x±2° | SIZE | | SHEET | 1 OF 2 | APPROVED | |
| .xx±0.15 | .xx±1° | A4 | | | | | |

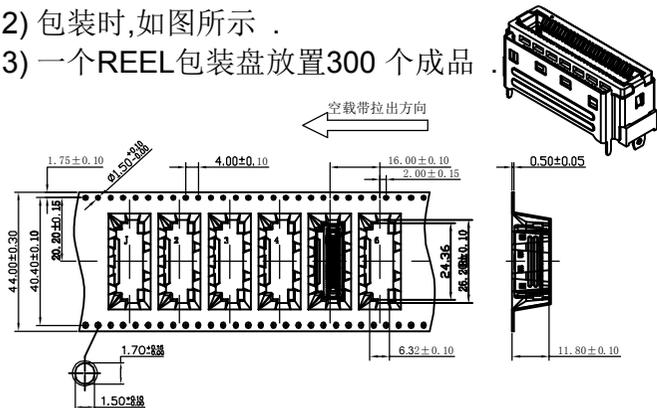
UNIT mm SCALE 1:1

OLN 东莞市欧联电子科技有限公司
 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.

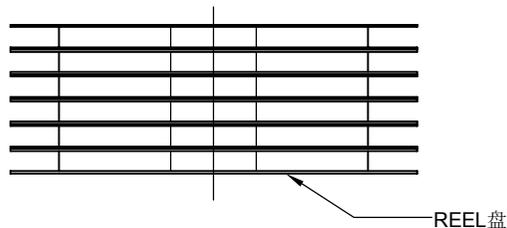
| | | |
|------|------------|----------------|
| REV. | ECN.NO. | MODIFY.CONTENT |
| X1 | 2024-02-10 | NEW |

包装作业图示及说明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

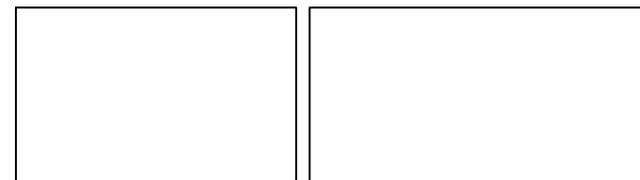
- 一. 1) 将成品一一放入REEL包装盘内,依同一方向放入
 2) 包装时,如图所示.
 3) 一个REEL包装盘放置300个成品.



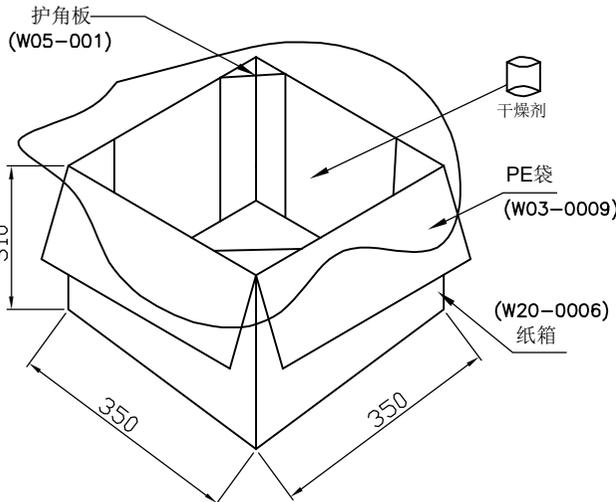
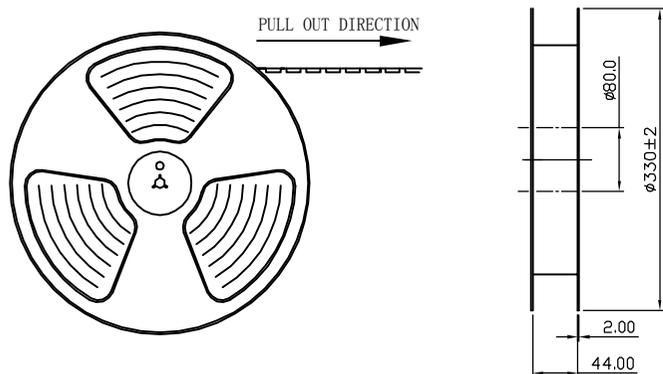
- 三. 1) 每箱装 6 盘REEL包装盘.
 2) 每箱放置 1800 PCS 的成品.



- 四. 1) 用TAPE將紙箱封實.



- 二. 1) 装盘前先把前面空15pcs产品,然后再开始装盘, 尾端也需空15pcs产品,上带加长200mm.
 2) 装满成品的REEL包装盘如下图所示.



備註 (REMARK)

1. 若有未裝滿之零數箱,必須以緩衝材塞滿.

| | | | | | | |
|-------------------|---------|----------------|----------|------------------------|----------|-----------------|
| GENERAL TOLERANCE | DWG.NO. | GENZ-056L10300 | PART.NO. | GENZ-056L103** | DRAWN | Tony 2024-02-10 |
| x.±0.50 | REV. | X1 | TITLE | GEN Z IC (SFF TA-1002) | CHECKED | |
| .x±0.25 | SIZE | | SHEET | 2 OF 2 | APPROVED | |
| .xx±0.15 | A4 | | | | | |

| | | | |
|--|----|-------|-----|
| UNIT | mm | SCALE | 1:1 |
| 东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD. | | | |